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## (30)Priority

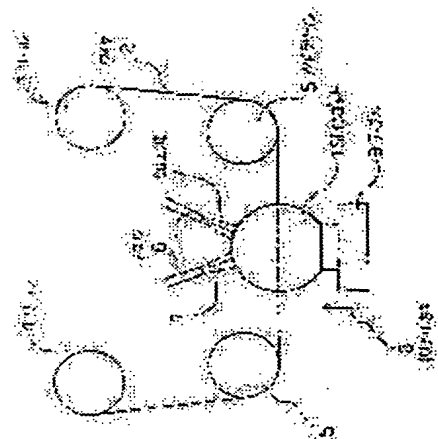
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## (54) METHOD OF CUTTING SI INGOT BY WIRE SAW

### (57)Abstract:

PURPOSE: To cut an Si ingot at high cutting speed by setting pH of processing liquid to pH9 or more and the temperature to 30°CW80°C in case of alkaline processing liquid, and pH to pH6WpH3 and the temperature to 25°CW65°C in case of acid processing liquid.

CONSTITUTION: pH of grinding powder added processing liquid 7 is set to pH9 or more in case of alkaline processing liquid and to pH6WpH3 in case of acid processing liquid and the temperature of the processing liquid is set to 30°CW80°C in case of alkaline processing liquid and to 25°CW65°C in case of acid processing liquid, and Si ingot 1 is cut with a wire saw 2. As a result, even 10-inch Si ingot 1 can be cut with the warp below 15µm or less.



## LEGAL STATUS

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